

Title (en)
Assembly for interconnecting circuit boards

Title (de)
Anordnung zum Verbinden von Leiterplatten

Title (fr)
Agencement destiné à relier des plaquettes

Publication
EP 2709212 B1 20191204 (DE)

Application
EP 12184174 A 20120913

Priority
EP 12184174 A 20120913

Abstract (en)
[origin: EP2709212A1] The arrangement has a printed circuit board (1) comprising a receptacle (3), and another printed circuit board (2) comprising a contact blade that is inserted into the receptacle. The latter circuit board has a lug (4) formed from printed circuit board material of the latter circuit board, where the lug is inserted into the receptacle for establishing electrical contact between the lug and the receptacle in a form-fit manner. The receptacle has a retaining area for the lug, where the retaining area is formed by a base plate with side walls.

IPC 8 full level
H01R 12/71 (2011.01); **H01R 12/72** (2011.01)

CPC (source: EP)
H01R 12/718 (2013.01); **H01R 12/721** (2013.01)

Citation (examination)
• US 2012264326 A1 20121018 - KUDO TAKAAKI [JP], et al
• US 2980878 A 19610418 - SWENGEL ROBERT C

Cited by
DE102020130750A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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